

BD034

Rev.E Mar.-2016

WR0459I 硅 PNP 三极管 封装 TO-18 硅 PNP 三极管 in a

BD034

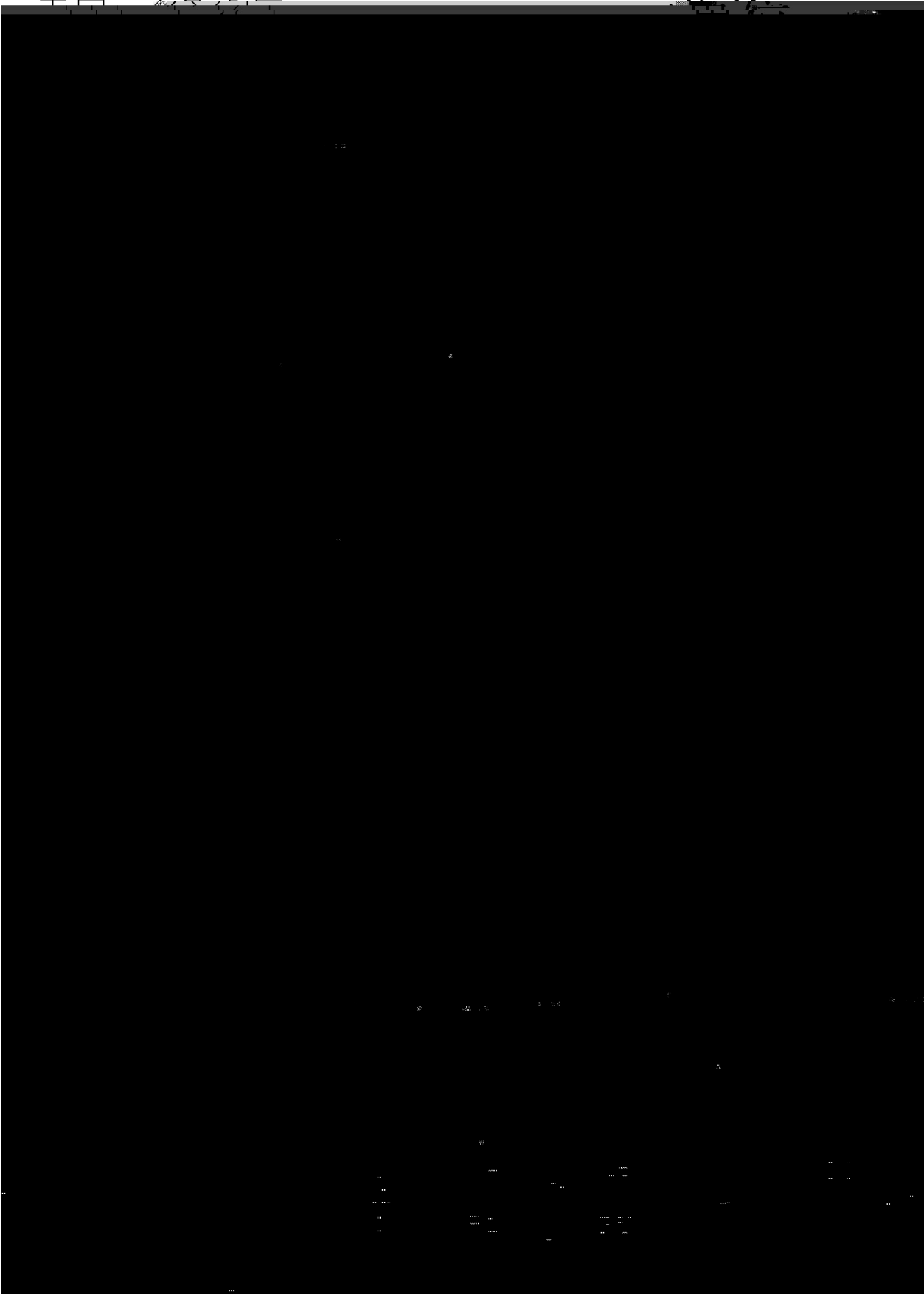
Rev.E Mar.-2016



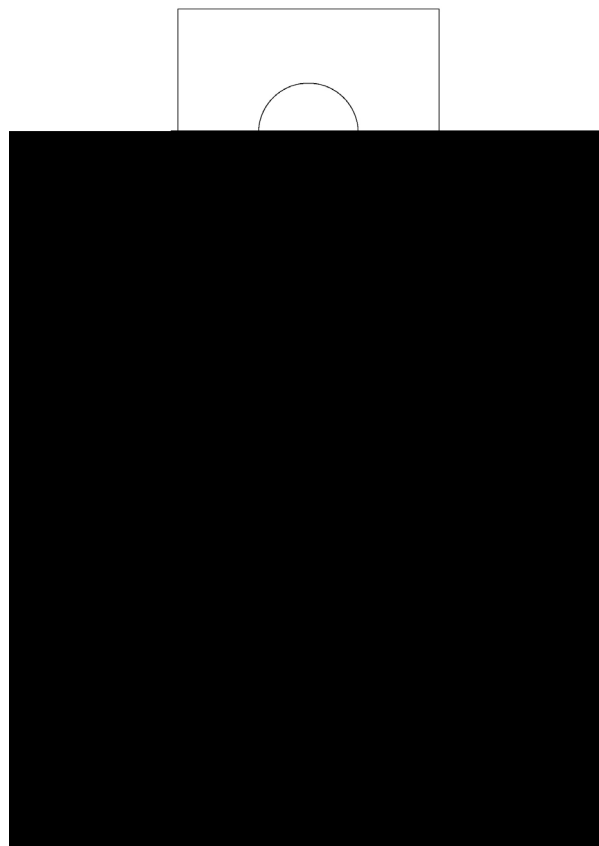
蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

/ Package Dimensions



/ Marking Instructions



Б " X

EU X

EG367 X

U X

---- X

Note:

BR:

BD034:

R X

****:

Б 3 " П

Б F β 3 N

Б k_{1H} 6 К П

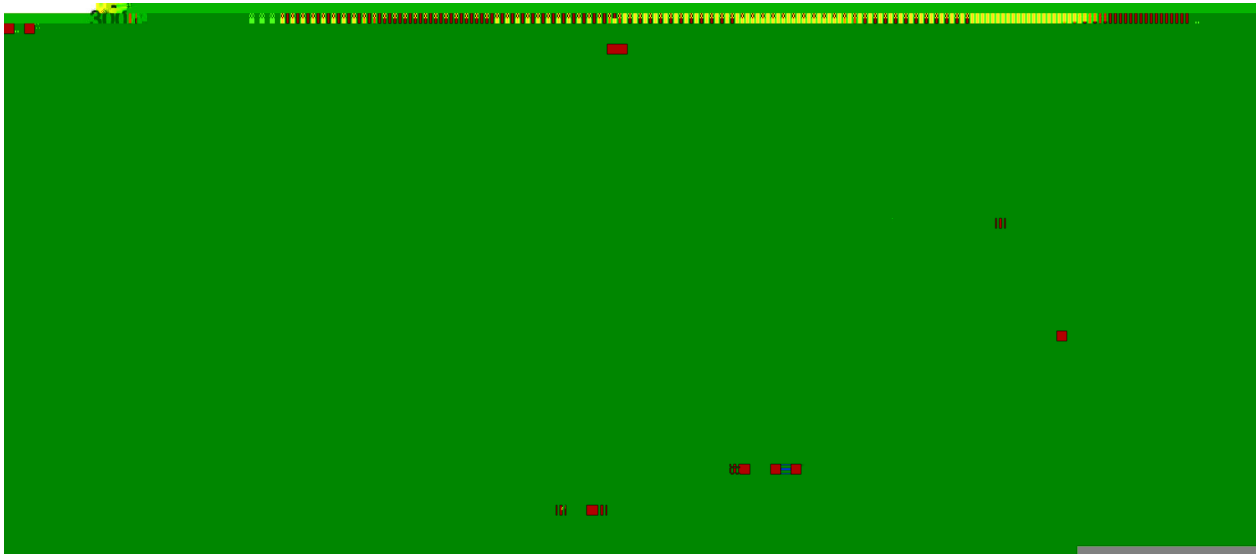
Б 1 F 1 N П 1 6 1 F 1 N П

Company Code

Product Type.

h_{FE} Classifications Symbol

Lot No. Code, code change with Lot No.


() / Temperature Profile for Dip Soldering(Pb-Free)


б " χ

1. 1. 25~150 °C, Time: 60~90sec;

2. 2. 255 °C, Duration: 5~0.5sec;

3. 3. Cooling Speed: 2~10 °C/sec.

Note:

1.Preheating:25~150 °C , Time:60~90sec.

2.Peak Temp.:255 °C , Duration:5~0.5sec.

3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270 ± 5

Time: 10 ± 1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

“Q” / BULK

Package Type	Units		Dimension	(unit mm ³)
	Units/Tube	Tubes/Inner Box		